

Bill of Materials

TI DESIGNS

TIDC-SPPBLE-SW-RD

Item	Qtv	Reference	Value	Part Description	Manufacturer	Manufacturer
iteiii	Qίγ					Part Number
1	5	C1 C2 C3 C4 C5	100nF	CAPACITOR, CERAMIC X7R, 100nF, 50V, -10%/+10%, -55DEGC/+125DEGC, 0603, SMD	MANUFACTURER SEL	CAPACITOR_0603_100nF_X7R_M_+/-10%_50V
2	1	J2	LSS-110-01-F-DV-A-TF	CONNECTOR, HEADER, HI-SPEED SOCKET, FEMALE, STRAIGHT, 2 ROWS,20 PINS, PITCH (SAMTEC	LSS-110-01-F-DV-A-TR
3	1	J3	09681535612	CONNECTOR, DSUB, FEMALE, RIGHT ANGLE, 2 ROWS, 9 PINS, PITCH 2.77mm, PTH	HARTING	09 68 153 5612
4	1	J4	MTB05008	CONNECTOR, TERMINAL BLOCK, FEMALE, RIGHT ANGLE, 1 ROW, 5 PINS, PITCH 3.5mm, PT	SAURO	MTB05008
5	1	P1	90120-0126	CONNECTOR, HEADER, MALE, STRAIGHT, 1 ROW, 6 PINS, PITCH 2.54MM, PTH	MOLEX	90120-0126
6	1	U1	MAX3232	IC, DIGITAL, INTERFACE, MULTICHANNEL RS-232 LINE DRIVER/RECEIVER, 3V TO 5.5V, TSS	TEXAS INSTRUMENTS	MAX3232EIPW

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